2SA0838 (2SA838)

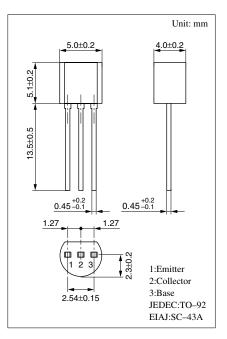
Silicon PNP epitaxial planer type

For high-frequency amplification Complementary to 2SC1359

Features

• High transition frequency f_T.

| Parameter | Symbol | Ratings | Unit |
|------------------------------|------------------|------------|------|
| Collector to base voltage | V _{CBO} | -30 | V |
| Collector to emitter voltage | V _{CEO} | -20 | V |
| Emitter to base voltage | V _{EBO} | -5 | V |
| Collector current | I _C | -30 | mA |
| Collector power dissipation | P _C | 250 | mW |
| Junction temperature | Tj | 150 | °C |
| Storage temperature | T _{stg} | -55 ~ +150 | °C |
| | | | |



Absolute Maximum Ratings (Ta=25°C)

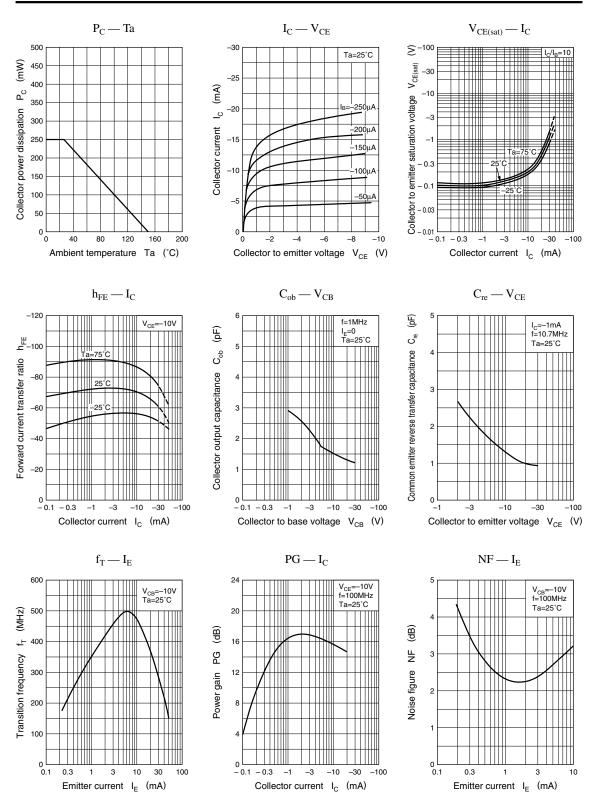
Electrical Characteristics (Ta=25°C)

| Parameter | Symbol | Conditions | min | typ | max | Unit |
|---|----------------------|---|-----|-------|-------|------|
| Collector cutoff current | I _{CBO} | $V_{CB} = -10V, I_E = 0$ | | | - 0.1 | μA |
| | I _{CEO} | $V_{CE} = -20V, I_B = 0$ | | | -100 | |
| Emitter cutoff current | I _{EBO} | $V_{EB} = -5V, I_C = 0$ | | | -10 | μΑ |
| Forward current transfer ratio | h _{FE} * | $V_{CE} = -10V, I_C = -1mA$ | 70 | | 220 | |
| Collector to emitter saturation voltage | V _{CE(sat)} | $I_{\rm C} = -10 {\rm mA}, I_{\rm B} = -1 {\rm mA}$ | | - 0.1 | | V |
| Base to emitter voltage | V _{BE} | $V_{CE} = -10V, I_C = -1mA$ | | - 0.7 | | V |
| Transition frequency | f _T | $V_{CB} = -10V$, $I_E = 1mA$, $f = 200MHz$ | 150 | 300 | | MHz |
| Noise figure | NF | $V_{CB} = -10V, I_E = 1mA, f = 5MHz$ | | 2.8 | 4.0 | dB |
| Reverse transfer impedance | Z _{rb} | $V_{CE} = -10V, I_C = -1mA, f = 2MHz$ | | 22 | 50 | Ω |
| Common emitter reverse transfer capacitance | C _{re} | $V_{CE} = -10V, I_C = -1mA,$ f = 10.7MHz | | 1.2 | 2.0 | pF |

*hFE Rank classification

| Rank | В | С |
|-----------------|----------|-----------|
| h _{FE} | 70 ~ 140 | 110 ~ 220 |

Note.) The Part number in the Parenthesis shows conventional part number.



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